	9144030070855050X9		
	A1 A3		0755-33810388
	(Printed Circuit Board PCB) (High Density Interconnection HDI) (Flexible Printed Circuit FPC) (Rigid Printed Circuit Board) ISO9001 ISO14001 ISO14064 OHSAS18001 ISO50001 QC080000		

					1		
			/	mg/L		mg/L	
				0.05	0.07	0.5	
				0.31	0.42	2	
				0.01	0.01	0.4	
				0.06	0.08	4	
			COD	57.25	79.05	160	
				0.15	0.21	0.5	
				11.75	16.22	30	
				0.05	0.07	0.5	
		DB44/1597-2015 1 DB44/1597-2015 1 200%					

					1		
			/	mg/m^3		mg/m^3	
				0.49	2.78	7	
				0.65	3.59	30	
				0.28	1.56	30	
				7.99	8.65	200	
				0.0008	0.005	0.5	
				0	N/A	0.05	
			VOCs	0.40	0.81	80	
		GB21900-2008 5 VOCs DB44/815-2010 2					

		( )	( )		
		160.00	160.00		
		9781.04	9781.04		

		(　)	(　)		

2.

6.

SMT

7.

		( )	( )		
	/	22.61	22.61		
		0.13	0.13		1.
		6.55	6.55		
		8.61	8.61		
		69.11	69.11		
		244.17	244.17		2.
		2.84	2.84		
		212.49	212.49		
		245.12	245.12		
		2.82	2.82		3.
		456.57	456.57		SMT
		19.66	19.66		
		122.13	122.13		
		17.90	17.90		
		11.89	11.89		4.
		7.21	7.21		
		20.65	20.65		
		6.98	6.98		

	Leq	Leq	Leq	Leq	
1	58.4	47.9	65	55	
1	58.8	50.7			
1	58.4	49.9			
1	58.0	47.5			

		2006 12	12000 /	
		2006 12	129.9 /	
	( )	2018 6	26.6 /	

( )		2005-12-23	[2005]213			

“

( )

”

			2017-2-27
	1 “ ” 2 “ ” 3		

	https://app.gdep.gov.cn/epinfo/ 2013 12 16 2015 10 23 2017 03 30 2018 12 31 2019 1 1 .

	1. COD pH 2.2018 5 15 (2012) 3. 500 RMB
	2018 9 , (SZDB/Z 151-2015) 5 .

1.

2. 2016 41

2019 1 15